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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/900,054	07/06/2001	Yi-Chuan Ding	JCLA6831	7810
7590	03/10/2004		EXAMINER	
J.C. Patents, Inc. 4 Venture Suite 250 Irvine, CA 92618				NGUYEN, KHIEM D
		ART UNIT	PAPER NUMBER	
		2823		
DATE MAILED: 03/10/2004				

Please find below and/or attached an Office communication concerning this application or proceeding.

<b>Office Action Summary</b>	Application No.	Applicant(s)
	09/900,054	DING ET AL.
Examiner	Art Unit	
Khiem D Nguyen	2823	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --  
Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133).
- Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

#### Status

1) Responsive to communication(s) filed on 10 December 2003.

2a) This action is FINAL. 2b) This action is non-final.

3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

4) Claim(s) 1-12 is/are pending in the application.

4a) Of the above claim(s) \_\_\_\_\_ is/are withdrawn from consideration.

5) Claim(s) \_\_\_\_\_ is/are allowed.

6) Claim(s) 1-12 is/are rejected.

7) Claim(s) \_\_\_\_\_ is/are objected to.

8) Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

#### Disposition of Claims

9) The specification is objected to by the Examiner.

10) The drawing(s) filed on 06 July 2001 is/are: a) accepted or b) objected to by the Examiner.

Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).

11) The proposed drawing correction filed on \_\_\_\_\_ is: a) approved b) disapproved by the Examiner.

If approved, corrected drawings are required in reply to this Office action.

12) The oath or declaration is objected to by the Examiner.

#### Priority under 35 U.S.C. §§ 119 and 120

13) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).

a) All b) Some \* c) None of:

- Certified copies of the priority documents have been received.
- Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
- Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

14) Acknowledgment is made of a claim for domestic priority under 35 U.S.C. § 119(e) (to a provisional application).

a)  The translation of the foreign language provisional application has been received.

15) Acknowledgment is made of a claim for domestic priority under 35 U.S.C. §§ 120 and/or 121.

#### Attachment(s)

1) <input type="checkbox"/> Notice of References Cited (PTO-892)	4) <input type="checkbox"/> Interview Summary (PTO-413) Paper No(s). _____.
2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948)	5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152)
3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO-1449) Paper No(s) _____.	6) <input type="checkbox"/> Other: _____

## DETAILED ACTION

### *Response to Amendment*

Applicant's arguments filed December 10<sup>th</sup>, 2003 have been fully considered but they are not persuasive.

The Rejection from paper No. 11 sent September 8<sup>th</sup>, 2003 is incorporated in this paper. It is presented here for convenience.

### *Claim Rejections - 35 USC § 103*

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

1. Claims 1-6 are rejected under 35 U.S.C. 103(a) as being unpatentable over Egawa et al. (U.S. Patent 6,376,278) in view of Belke, Jr. et al. (U.S. Patent 6,326,241) and Hung (U.S. Patent 6,380,624).

In re claim 1, Egawa teaches a flip chip packaging process comprising (col. 4, line 9 to col. 8, line 9 and **FIGS. 2(A)-9(A)**): providing a wafer **12** having a plurality of chips **18** formed thereon, wherein each chip has an active surface **18a** (**FIG. 2A**); providing a plurality of individual substrates **28**, wherein each substrate includes a plurality of package units (**FIGS. 2(A)-(C) and 8(A)-(C)**); respectively mounting the substrates onto the wafer such that each package unit corresponds to each chip wherein two neighboring substrates are separated by a gap (col. 4, lines 9-17 and **FIG. 2B**); filling an underfill material **34** between the substrates and the wafer, wherein the underfill

material being introduced through the gaps between the substrates and from the boundary of the wafer (col. 4, lines 35-47 and **FIG. 2C**); solidifying the underfill material (col. 4, line 45); and dicing the wafer and the substrates to form a plurality of individualized packages 66, each individualized package including one chip and one package unit wherein the surface of each package unit is equal to the active surface of the corresponding chip (col. 7, lines 55-62).

In re claims 1, 5, and 6, Egawa fails to teach that each chip has an active surface provided with a plurality of bonding pads and each package unit having a plurality of contact pads wherein a gold bump is formed on each bonding pad and the contact pads are respectively connected to the corresponding bumps.

Belke teaches a flip-chip **12** has an active surface provided with a plurality of bonding pads **14** and a substrate having a plurality of bonding pads **20** wherein a gold bump **16** is formed on each bonding pad of the flip-chip and the bonding pads of the substrate are respectively connected to the corresponding bumps (col. 4, line 58 to col. 5, line 12 and **FIGS. 1-2**). It would have been obvious to one of ordinary skill in the art of making semiconductor devices to incorporate Belke's teaching into Egawa's method because doing so can provide the electrical inputs and outputs to the flip-chip **12** (col. 4, lines 63-66 and **FIGS. 1-2**).

In re claims 2-4, Egawa fails to teach that each substrate includes a plurality of patterned conductive layers alternately laminated with a plurality of insulating layers wherein the material of the insulating layer is FR-4, FR-5, bismaleimide triazine (BT), polyimide, or materials composite of epoxy and ceramic.

Hung teaches a substrate **228** includes a plurality of patterned copper films (**236a** and **236b**) alternately laminated with a plurality of insulating layers **230** wherein the material of the insulating layer is FR-4, FR-5 and bismaleimide triazine (BT) (col. 4, lines 6-20 and **FIG. 4**). It would have been obvious to one of ordinary skill in the art of making semiconductor devices to incorporate Hung's teaching into Egawa's method because doing so can make the production and the assembly of the memory module easier (col. 1, lines 65-67).

2. Claims 7-12 are rejected under 35 U.S.C. 103(a) as being unpatentable over Egawa et al. (U.S. Patent 6,376,278) in view of Belke, Jr. et al. (U.S. Patent 6,326,241) and Hung (U.S. Patent 6,380,624).

In re claim 7, Egawa teaches a flip chip packaging process comprising (col. 7, line 2 to col. 8, line 9 and **FIGS. 7-9(A)**): providing a wafer **12** having a plurality of chips **18** formed thereon, wherein each chip has an active surface **18a** (**FIG. 2A**); providing a plurality of individual substrates **28**, wherein each substrate includes a plurality of package units (**FIGS. 2(A)-(C)** and **8(A)-(C)**); respectively mounting the substrates onto the wafer such that each package unit corresponds to one chip wherein two neighboring substrates are separated by a gap (col. 4, lines 9-17 and **FIG. 2B**); filling an underfill material **34** between the substrates and the wafer, wherein the underfill material being introduced through the gaps between the substrates and from the boundary of the wafer (col. 4, lines 35-47 and **FIG. 2C**); solidifying the underfill material (col. 4, line 45); and dicing the wafer and the substrates to form a plurality of individualized packages **66**, each individualized package including one package unit and one chip wherein the surface of

each package unit is equal to the active surface of the corresponding chip (col. 7, lines 55-62).

In re claims 7 and 11, Egawa fails to teach that each chip provided with a plurality of bonding pads and each package unit having a plurality of contact pads wherein a gold bump is formed on each contact pad and the bonding pads are respectively connected to the corresponding bumps.

Belke teaches a flip-chip **12'** has an active surface provided with a plurality of contact pads **20'** and a substrate **18'** having a plurality of bonding pads **14'** wherein a gold bump **16'** is formed on each bonding pad of the substrate and the contact pads of the flip-chip are respectively connected to the corresponding bumps (col. 4, lines 66-67 and col. 6, lines 30-48 and **FIGS. 2-3**). It would have been obvious to one of ordinary skill in the art of making semiconductor devices to incorporate Belke's teaching into Egawa's method because doing so can provide the electrical inputs and outputs to the flip-chip **12** (col. 4, lines 63-66 and **FIG. 3**).

In re claims 8-10, Egawa fails to teach that each substrate includes a plurality of patterned conductive layers alternately laminated with a plurality of insulating layers wherein the material of the insulating layer is FR-4, FR-5, bismaleimide triazine (BT), polyimide, or materials composite of epoxy and ceramic.

Hung teaches a substrate **228** includes a plurality of patterned copper films (**236a** and **236b**) alternately laminated with a plurality of insulating layers **230** wherein the material of the insulating layer is FR-4, FR-5 and bismaleimide triazine (BT) (col. 4, lines 6-20 and **FIG. 4**). It would have been obvious to one of ordinary skill in the art of

making semiconductor devices to incorporate Hung's teaching into Egawa's method because doing so can make the production and the assembly of the memory module easier (col. 1, lines 65-67).

***Response to Amendment***

***Response to Applicant's Arguments***

Applicant's arguments filed December 10<sup>th</sup>, 2003 have been fully considered but they are not persuasive.

In response to Applicant's argument that nothing is taught or suggested in Egawa's disclosure in relating to "providing a plurality of individual substrates, each substrate including a plurality of package units, each package unit corresponding to one chip of the wafer" as claimed in this invention, examiner respectfully disagree.

Applicants are directed to (col. 4, lines 9 to col. 7, line 12 and FIGS. 2-7), where Egawa discloses providing a plurality of individual substrates (FIGS. 2(A)-(C): 28), each substrate including a plurality of package units (col. 4, lines 9-26), each package unit corresponding to one chip (FIGS. 2(A)-(C): 18) of the wafer. Egawa also discloses dispense a resin material (FIG. 2(C): 34) between the substrate and the wafer (col. 4, lines 35-44), wherein the resin material is introduced through the gaps between the substrates and from the boundary of the wafer. Thereafter, the resin material is solidifying (col. 4, lines 44-46) and dicing the wafer and the substrates to form a plurality of individualized packages (col. 7, lines 55-62). As shown in FIG. 7, each individualized package including one chip and one package unit. By doing this, a manufacturing time period and a manufacturing cost may be reduced (col. 4, lines 63-64).

For these reasons, examiner holds the rejection proper.

***Conclusion***

**THIS ACTION IS MADE FINAL.** Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

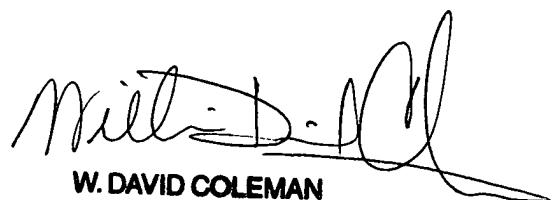
A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Khiem D Nguyen whose telephone number is (571) 272-1865. The examiner can normally be reached on Monday-Friday (8:00 AM - 5:00 PM).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Olik Chaudhuri can be reached on (571) 272-1855. The fax phone numbers for the organization where this application or proceeding is assigned are (703) 305-3432 for regular communications and (703) 305-3432 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-0956.

K.N.  
March 4, 2004



W. DAVID COLEMAN  
PRIMARY EXAMINER